

A B C D E F G H

ASSEMBLY DRAWING NOTES:

1. THE PCB ASSEMBLY SHALL BE COMPLIANT WITH THE ROHS2 DIRECTIVE 2011/65/EU. THIS SHALL INCLUDE, AT A MINIMUM, ALL THE CONSTITUENT MATERIALS AND ANY OTHER ADDITIVES THAT MAY BE INCLUDED OR TRANSFERRED INTO THE FINAL PRODUCT DURING THE MANUFACTURING PROCESS. THE SUPPLIER OF THIS PCB ASSEMBLY SHALL BE ABLE TO PROVIDE DOCUMENTATION UPON REQUEST DEMONSTRATING COMPLIANCE TO THE DIRECTIVE.

2. ASSEMBLY SHALL BE ACCEPTABLE AND REJECTABLE AND INSPECTED TO IPC-A-610, CLASS 2.

3. REWORK, REPAIR, OR MODIFICATIONS MUST COMPLY WITH IPC-7711 AND IPC-7721 CLASS 2.

4. EXCEPTIONS TO NOTE 3: LIFTED LAND REPAIR, LAND REPAIR, LIFTED CONDUCTORS, AND PAD REPAIR IS NOT ACCEPTABLE.

5. EACH LOT SHALL HAVE A CERTIFICATE OF COMPLIANCE TO CERTIFY THAT MATERIALS SPECIFIED ON THE BILL OF MATERIALS HAVE BEEN USED AND THAT THE ASSEMBLY HAS BEEN ASSEMBLED IN COMPLIANCE WITH THE AGREED QUALITY PLAN.

6. THE ASSEMBLY SHALL BE LEGIBLY IDENTIFIED USING NON-CONDUCTIVE EPOXY INK OR A NON-CONDUCTIVE PERMANENT LABEL LOCATED IN THE AREA(S) INDICATED. THE IDENTIFIERS SHALL CONSIST OF THE MBI NUMBER (INCLUDING REVISION) AND THE BOARD'S SERIAL NUMBER (TO BE GENERATED BY THE ASSEMBLER). IF THIS ASSEMBLY DRAWING SHOWS THE LOCATION IS OFF THE BOARD, THE LABEL SHOULD BE PLACED ON A TAG THAT IS ATTACHED TO THE BOARD.

7. COMPONENTS WITH PIN ONE DESIGNATOR OR POLARIZATION MARKINGS SHALL BE PLACED AS INDICATED ON THE ASSEMBLY DRAWING.

8. APPROPRIATE ESD PRECAUTIONS SHALL BE USED WHILE BUILDING OR HANDLING THIS ASSEMBLY.

9. COMPONENT LEADS IN PLATED-THROUGH HOLES SHALL BE TRIMMED TO EXTEND NO GREATER THAN 1.8 MM FROM THE PLATING SURFACE.



